



# SOT116-1

DIP22, plastic dual in-line package; 22 leads, 2.54 mm pitch,  
27.94 mm x 8.7 mm x 3.81 mm body

11 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP22
<b>Package type industry code</b>	DIP22
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	060G07
<b>JEDEC package outline code</b>	MS-010
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	27-12-1999
<b>Manufacturer package code</b>	SOT116

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	27.69	27.94	28.19	mm
package width	8.38	8.7	9.02	mm
seated height	-	4.83	-	mm
package height	-	3.81	-	mm
nominal pitch	-	2.54	-	mm
actual quantity of termination	-	22	-	



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2 Package outline

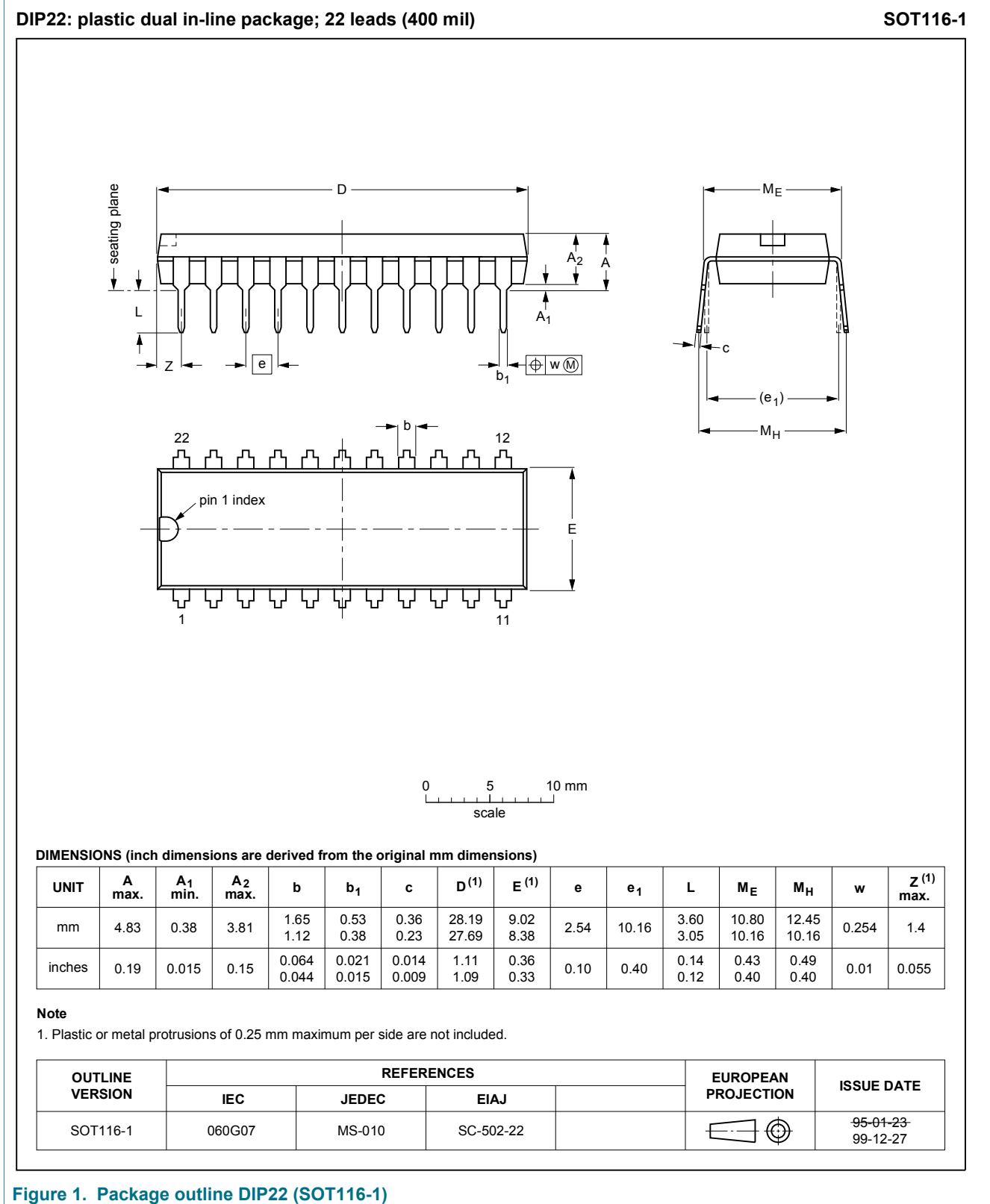


Figure 1. Package outline DIP22 (SOT116-1)

### 3 Legal information

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